



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC-4101B

with Amendments 1 & 2

Specification for Base
Materials for Rigid and
Multilayer Printed Boards

**IPC-4101B with
Amendments 1 & 2**

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Specification for Base Materials for Rigid and Multilayer Printed Boards

Developed by the Laminate/Prepreg Materials Subcommittee (3-11) of
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Table of Contents

1	SCOPE	1	3.3	Manufacturer Quality Profile	6
1.1	Classification	1	3.4	Qualification Testing	6
1.1.1	Specification Sheet Description	1	3.4.1	Qualification Testing of Laminate	7
1.1.2	Nominal Laminate Thickness	1	3.4.2	Qualification Testing of Prepreg	9
1.1.3	Metal Cladding Type and Nominal Weight/Thickness	1	3.5	Verification of Manufacturer's Quality System	9
1.1.3.1	Metal Cladding Type	1	3.6	Conflict	9
1.1.3.2	Nominal Weight/Thickness	1	3.7	Materials	9
1.1.4	Thickness Tolerance (Laminate)	1	3.7.1	Metal Cladding	9
1.1.5	Surface Quality Class	2	3.7.2	Reinforcement Fabric	9
1.1.6	Reinforcement Style	2	3.7.3	Resin Systems	9
1.1.7	Prepreg Parameters	2	3.8	General Requirements	9
1.1.8	Color	2	3.8.1	Fabricated Sheets and Panels	9
1.1.8.1	Contrast Agents	2	3.8.1.1	Fabricated Laminate Sheet Material	9
1.2	Dimensions and Tolerances	3	3.8.1.2	Fabricated Laminate Panel Material	9
1.2.1	Metric and English Measurements	3	3.8.1.3	Fabricated Prepreg Panels	9
			3.8.1.4	Fabricated Prepreg Rolls	9
2	APPLICABLE DOCUMENTS	3	3.8.2	Inspection Lot	9
2.1	IPC	3	3.8.2.1	Inspection Lot for Laminate	9
2.2	National Conference of Standards Laboratories (NCSL)	4	3.8.2.2	Inspection Lot for Prepreg	9
2.3	International Standards	4	3.8.2.3	Preparation of Samples	10
2.4	Underwriters Laboratories (UL)	4	3.8.2.4	Etching Process and Etchant Removal for Copper Foil Specimens	10
2.5	European Union	4	3.8.2.5	Standard Laboratory Conditions	10
2.6	ASTM International	4	3.8.3	Visual Properties	10
			3.8.3.1	Laminate Visual Properties	10
3	REQUIREMENTS	5	3.8.3.1.1	Foil Indentations	10
3.1	Terms and Definitions	5	3.8.3.1.2	Wrinkles	10
3.1.1	Qualification Assessment	5	3.8.3.1.3	Scratches	10
3.1.2	Quality Conformance Testing	5	3.8.3.1.4	Plastic Surface Finish of Metal-Clad Single-Sided Base Material	10
3.1.3	Manufacturer's Quality System	5	3.8.3.1.5	Surface Finish of Foil after Curing – Except Double Treat	10
3.1.4	Process Control Testing	5	3.8.3.1.6	Surface and Subsurface Imperfections	10
3.1.5	Self Declaration	5	3.8.3.2	Prepreg Visual Properties	11
3.1.6	Quality Assessment Data	5	3.8.3.2.1	Inclusions	11
3.1.7	Sample Qualification	5	3.8.3.2.2	Impregnation Imperfections	11
3.1.8	Production Data	5	3.8.4	Dimensional	11
3.1.9	Customer Test Data	5	3.8.4.1	Length and Width	11
3.1.10	Internal Assessment	5	3.8.4.1.1	Length and Width of Laminate	11
3.1.11	Individual Customer Audit	5	3.8.4.1.2	Length and Width of Prepreg	11
3.1.12	Independent Third Party Assessment	5	3.8.4.1.3	Prepreg Roll Width	11
3.1.13	Epoxy, Multifunctional	5	3.8.4.1.4	Prepreg Roll Length	12
3.1.14	Epoxy, Difunctional	5	3.8.4.2	Thickness	12
3.1.15	AABUS	5			
3.2	Specification Sheets	6			

3.8.4.2.1	Class A, B, and C Laminate Materials	12	3.10.1.6	Glass Transition Temperature (T_g) (Optional)	15
3.8.4.2.2	Class D Laminate Materials	12	3.10.1.7	Delta T_g (Optional)	16
3.8.4.2.3	Class K, L, M Laminate Materials	12	3.10.1.8	Coefficient of Thermal Expansion (CTE) (Optional)	16
3.8.4.2.4	Thickness Tolerance of Laminate Materials	12	3.10.1.9	Halogen Content (Optional)	16
3.8.4.3	Bow and Twist of Laminate Materials	13	3.10.1.10	Decomposition Temperature (Optional Test)	16
3.8.4.3.1	Sheets and Panels with Both Dimensions ≥ 300 mm [11.81 in]	13	3.10.1.11	Z-Axis CTE	16
3.8.4.3.2	Panels with One or Both Dimensions < 300 mm [11.81 in]	13	3.10.1.12	Time to Delaminate (TMA) (Optional Test)	16
3.9	Physical Requirements	13	3.10.2	Chemical Requirements of Prepreg Materials	16
3.9.1	Physical Requirements of Laminate Materials	13	3.10.2.1	Flammability	16
3.9.1.1	Peel Strength	13	3.10.2.2	Chemical Resistance (Optional)	16
3.9.1.1.1	Peel Strength after Thermal Stress	14	3.10.2.3	Presence of Dicyandiamide (Dicy) (Optional)	16
3.9.1.1.2	Peel Strength at Elevated Temperature	14	3.11	Electrical Requirements	16
3.9.1.1.3	Peel Strength after Process Chemicals (Optional)	14	3.11.1	Electrical Requirements of Laminate Materials	16
3.9.1.2	Dimensional Stability	14	3.11.1.1	Permittivity	16
3.9.1.3	Flexural Strength	14	3.11.1.2	Loss Tangent	16
3.9.1.4	Flexural Strength at Elevated Temperature	14	3.11.1.3	Volume Resistivity	16
3.9.1.5	Thermal Conductivity	14	3.11.1.4	Surface Resistivity	16
3.9.2	Physical Requirements of Prepreg Materials	14	3.11.1.5	Arc Resistance	16
3.9.2.1	Resin Content	14	3.11.1.6	Dielectric Breakdown	16
3.9.2.1.1	Resin Content Percent (RC) (by Treated Weight)	14	3.11.1.7	Electric Strength	16
3.9.2.1.2	Resin Content Percent (RC) (by Burn-Off)	14	3.11.2	Electrical Requirements of Prepreg Materials	16
3.9.2.1.3	Treated Weight Total (TW)	14	3.11.2.1	Permittivity	17
3.9.2.1.4	Variation Within a Panel	14	3.11.2.2	Loss Tangent	17
3.9.2.2	Flow Parameter	14	3.11.2.3	Electric Strength	17
3.9.2.2.1	Resin Flow Percent (MF)	14	3.12	Environmental Requirements	17
3.9.2.2.2	Scaled Flow Thickness (SC)	14	3.12.1	Environmental Requirements of Laminate Materials	17
3.9.2.2.3	No Flow (NF)	14	3.12.1.1	Moisture Absorption	17
3.9.2.2.4	Rheological Flow (RE)	15	3.12.1.2	Fungus Resistance	17
3.9.2.2.5	Delta H (DH)	15	3.12.1.3	Pressure Vessel (Optional)	17
3.9.2.2.6	Percent Cure (PC)	15	3.12.1.4	Conductive Anodic Filament (CAF) Growth (Optional)	17
3.9.2.2.7	Gel Time (GT) (Optional Test)	15	3.12.2	Environmental Requirements of Prepreg Materials	17
3.9.2.2.8	Volatile Content (VC) (Optional Test)	15	3.12.2.1	Fungus Resistance	17
3.9.2.2.9	Thermal Conductivity (Prepreg Reference)	15	3.13	Substitutability	17
3.10	Chemical Requirements	15	3.13.1	Substitutability of Classes of Pits and Dents	17
3.10.1	Chemical Requirements of Laminate Materials	15	3.13.2	Substitutability of Classes of Thickness Tolerance	17
3.10.1.1	Flammability	15	3.13.3	Remarking of Substituted Laminates	17
3.10.1.2	Thermal Stress	15			
3.10.1.3	Solderability	15			
3.10.1.4	Chemical Resistance (Optional)	15			
3.10.1.5	Metal Surfaces Cleanability	15			

3.14 Marking 17

3.14.1 Marking Laminate Materials 17

3.14.2 Marking Prepreg Materials 17

3.14.3 Marking of Shipping Containers 17

3.15 Workmanship 18

3.16 Material Safety 18

3.17 Prepreg Shelf Life 18

4 QUALITY ASSURANCE PROVISIONS 18

4.1 Quality System 18

4.2 Responsibility for Inspection 18

4.2.1 Test Equipment and Inspection Facilities 18

4.3 Qualification Testing 18

4.3.1 Samples 18

4.3.2 Frequency 18

4.3.3 Laminator Qualification Profile 18

4.3.4 Changes in Composition 18

4.3.5 Qualification Data Retention 18

4.4 Quality Conformance Inspection 18

4.4.1 Frequency 18

4.4.2 Acceptance Criteria 19

4.4.3 Rejected Lots 19

4.4.4 Conformance Data Retention 19

4.4.5 Certificate of Conformance 19

4.5 Statistical Process Control (SPC) 19

5 PREPARATION FOR DELIVERY 19

5.1 Packaging Materials 19

5.2 Authorized Distributors 19

6 NOTES 20

6.1 Ordering Information 20

6.1.1 Ordering Data for Laminate Materials 20

6.1.2 Ordering Data for Prepreg Materials 20

6.2 New Materials 20

7 KEYWORDS 20

7.1 Keyword Search Terms (Electronic/Soft Copy Searches) 21

7.2 Segmented Keyword Search Terms and All Specification Sheets that Use the Specific Keywords for Searching 21

7.3 Keyword Search Terms for All Specification Sheets 22

Figures

Figure 3-1 Thickness Measurements for Laminates 12

Tables

Table 1-1 Metal Cladding Types 2

Table 1-2 Copper Foil Weight and Thickness 3

Table 3-1 Reference Information and Test Frequency of Laminate 6

Table 3-2 Reference Information and Test Frequency of Prepreg 8

Table 3-3 Point Value for Longest Dimensions of Indentation 10

Table 3-4 Surface Quality Classification 10

Table 3-5 Permissible Variation in Length and Width of Laminates 11

Table 3-6 Permissible Variation in Length and Width of Prepregs 12

Table 3-7 Thickness and Tolerances for Laminates 13

Table 3-8 Permissible Bow and Twist for Laminates, % .. 13

Table 3-9 Flammability Requirements 15

Table 4-1 Quality Conformance Plan for Monthly, Quarterly and Annual Tests – Laminate 19

Table 4-2 Quality Conformance Plan for Monthly, Quarterly and Annual Tests – Prepreg 19

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Specification for Base Materials for Rigid and Multilayer Printed Boards

1 SCOPE

This specification covers the requirements for base materials, herein referred to as laminate or prepreg, to be used primarily for rigid or multilayer printed boards for electrical and electronic circuits.

1.1 Classification The system shown below identifies clad and unclad laminate or prepreg base materials. The specification sheets serve as a cross-reference connecting the outlined callout system in this document to previously used systems.

Example for laminate base materials where this specification is referenced:

L	Material Designator (see 1.1.1)
25	Specification Sheet Number (see 1.1.1)
1500	Nominal Laminate Thickness (see 1.1.2)
C1/C1	Metal Cladding Type and Nominal Weight/Thickness (see 1.1.3)
A	Thickness Tolerance Class (see 1.1.4)
A	Surface Quality Class (see 1.1.5)

Example for prepreg base materials where this specification is referenced:

P	Material Designator (see 1.1.1)
25	Specification Sheet Number (see 1.1.1)
E7628	Reinforcement Style (see 1.1.6)
TW	Resin Content Method (see 1.1.7)
RE	Flow Parameter Method (see 1.1.7)
VC	Optional Prepreg Method (see 1.1.7)

1.1.1 Specification Sheet Description At the end of this document is a series of specification sheets. Each specification sheet outlines requirements for both laminate and prepreg for each product grade. The specification sheets are organized by a specific reinforcement type, resin system, and/or construction and are provided with a specification sheet number for ordering purposes. For convenience, the laminate and prepreg requirements for materials of the like composition are on the same specification sheet. Material Designator “L” indicates laminate material and Material Designator “P” indicates prepreg material as shown in designation examples in 1.1. When certifying to multiple specification sheets, the strongest performance requirements **shall** apply.

The headings for each specification sheet include reference definitions for the material, which cover the reinforcements, resin systems, flame retardants, and fillers used, as well as its other known identifications and glass transition temperature, T_g . The specific line items within the specification sheets are the requirements that material **shall** meet in order to be certified to this specification.

1.1.2 Nominal Laminate Thickness The nominal thickness is identified by four digits. For all substrates covered by this document, thicknesses may be specified or measured either over the cladding or over the dielectric (see 1.1.4 and 3.8.4.2). For metric specification, the first digit represents whole millimeters, the second represents tenths of millimeters, etc. For orders requiring English units, the four digits indicate the thickness in ten-thousandths of an inch (tenths of mils). In the example shown in 1.1, 1500 is designated for the English unit usage of 0600 for a laminate with thickness of 1.5 mm [59.1 mil].

1.1.3 Metal Cladding Type and Nominal Weight/Thickness The type and nominal weight or thickness of the metallic cladding for laminate base material is identified by five designators. The first and fourth designators indicate the type of cladding; the third designator is a slash mark that differentiates sides of the base material; the second and fifth designators indicate the nominal weight or thickness of the metallic cladding.

1.1.3.1 Metal Cladding Type The types of metallic cladding and the designators representing them are shown in Table 1-1. Table 1-1 is provided as a reference only. The referee document is the latest version of IPC-CF-148, IPC-4562, or IPC-CF-152 as appropriate. Cladding types C and R, and cladding types H and S, may be used interchangeably as agreed upon between user and supplier. Cladding type H can be used for type C and type S can be used for type R. Cladding type R may be substituted for type C, and cladding type S may be substituted for type H.

1.1.3.2 Nominal Weight/Thickness The weight or thickness of metallic cladding and the designators representing them are listed in Table 1-2. Table 1-2 is provided as a reference only. The referee document is the latest version of IPC-CF-148, IPC-4562, or IPC-CF-152 as appropriate.

1.1.4 Thickness Tolerance (Laminate) The class of thickness tolerance for laminate base material is identified by either A, B, C, D, K, L, M, or X (as agreed upon